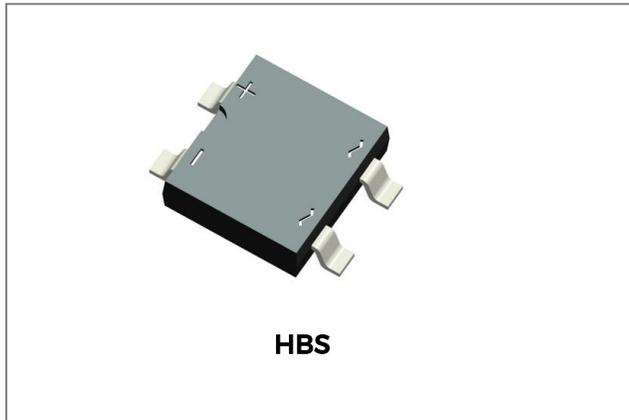


## HBS402 THRU HBS410

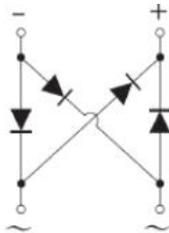
### Glass Passivated Single-Phase 4.0Amp Surface Mount Bridge Rectifier



#### Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

#### Circuit Diagram



#### Mechanical Data

- Case: HBS;
- Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed: Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;

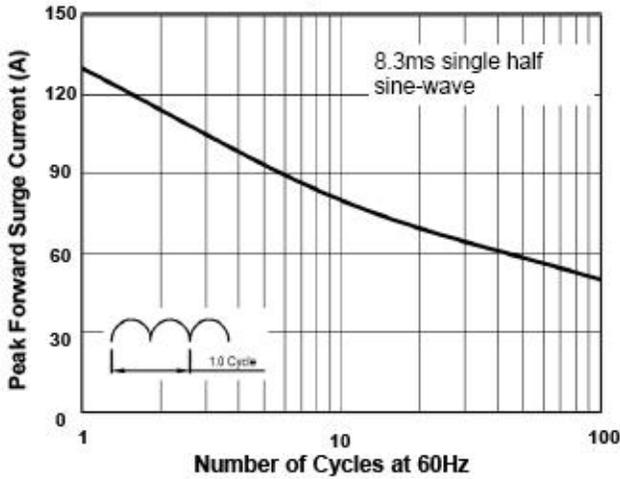
#### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

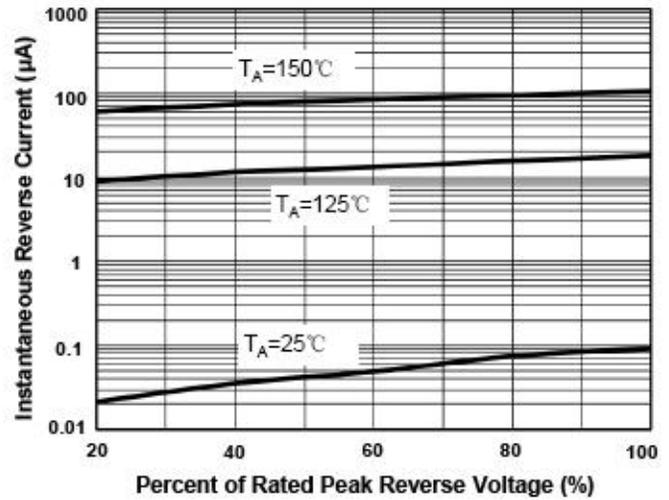
Type Number	Symbol	HBS402	HBS404	HBS406	HBS408	HBS410	Units	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>DC</sub>	200	400	600	800	1000	V	
RMS Reverse Voltage	V <sub>RMS</sub>	140	280	420	560	700	V	
Maximum average forward rectified output current at @T <sub>A</sub> =25°C	I <sub>(AV)</sub>	4						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	130						A
Rating for fusing (t<8.3ms)	I <sup>2</sup> t	70						A <sup>2</sup> sec



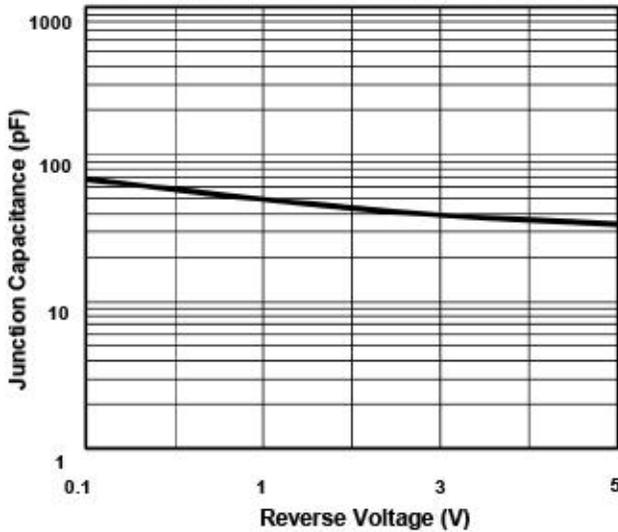
**FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode**



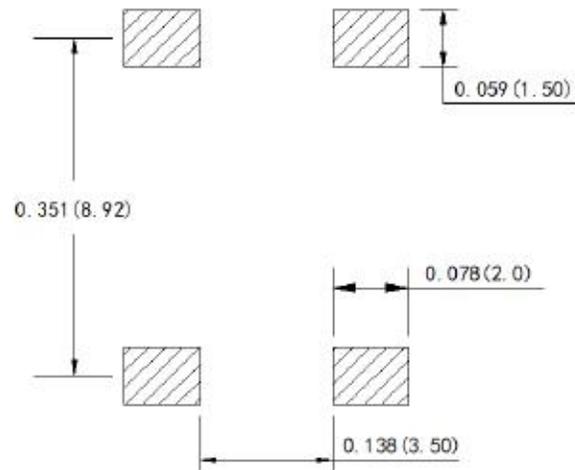
**FIG.4 Typical Reverse Characteristics per Diode**



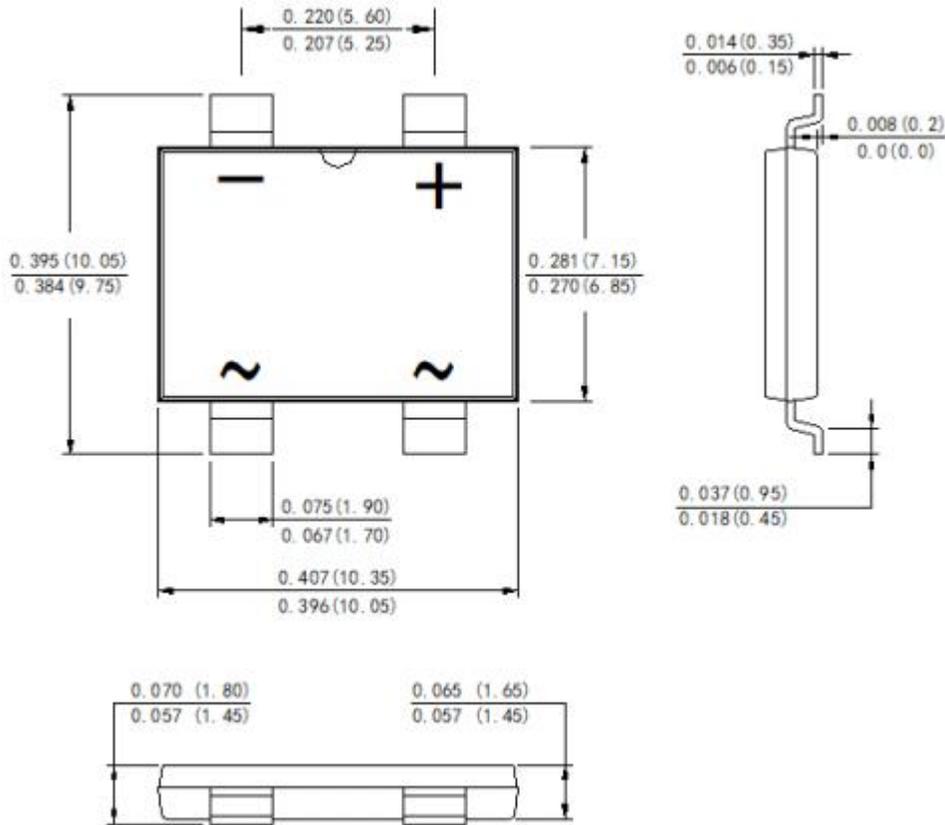
**FIG.5 Typical Junction Capacitance per Diode**



**Suggested PCB printfoot layout** Unit: inches (mm)



**Mechanical Dimensions HBS(Inches/Millimeters)**

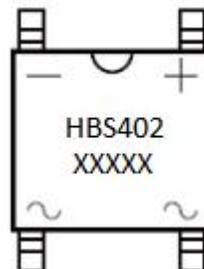


**Ordering Information**

Device	Package	Plating	Shipping
HBS402 THRU HBS410	HBS (Pb-Free)	Pure Sn	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**



Where XXXXX is YYWWL

HBS402 = Type Number  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL94V-0



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